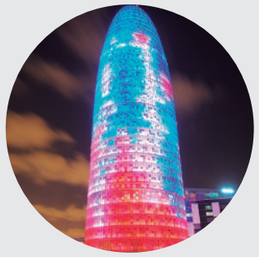
Application Fields

Automotive Lighting

FRONT LIGHTS

REAR & INTERIOR LIGHTS



Lighting-LED

POWER LED PACKAGES

STREET LIGHTING

STADIUMS & ARENAS

ARCHITECTURAL

DECORATIVE

INDUSTRAL
& HORTICULTURE

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Aismalibar

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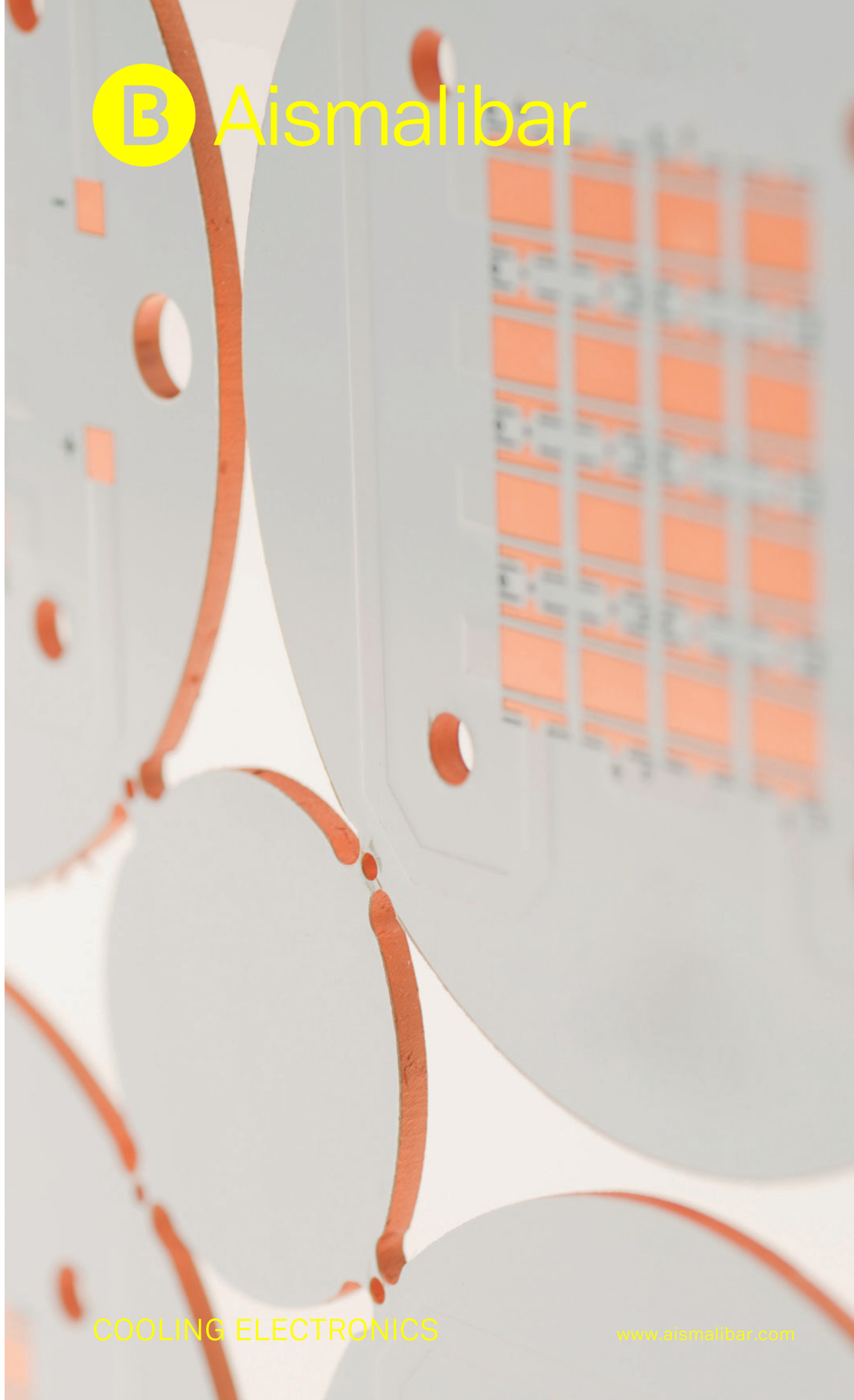
FASTHERM



Aismalibar

COOLING ELECTRONICS

www.aismalibar.com

FASTHERM

Excellent for high temperature applications
Extremely low thermal impedance
V-0 / Halogen free / High MOT values
Produced with RA copper to grant conformable properties
Withstands Lead Free Soldering process
Ideal for pedestrian technology

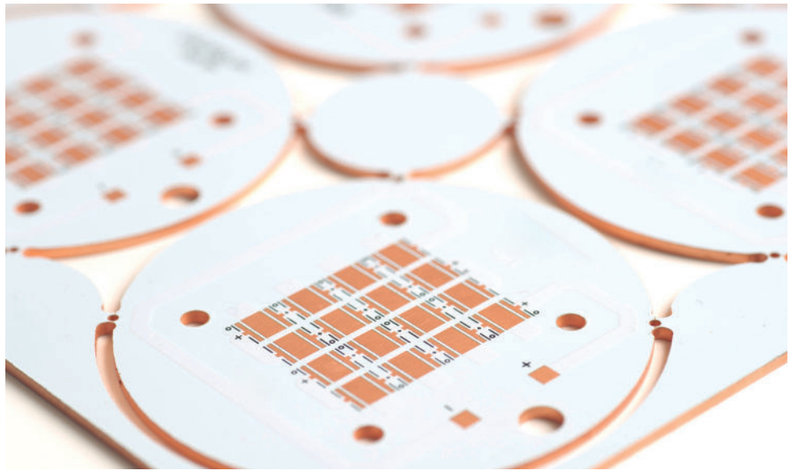
UL Approved QMTS2
File: E47820 IPC-4101

RoHS 3 / REACH
Last updated compliance directive

FASTHERM is a new technology developed by AISMALIBAR to achieve a faster thermal transition from the LED thermal pad to the heat sink.

By using FASTHERM technology LEDs operate at 30 to 50ºC lower in temperature due to the direct thermal transition from the thermal pad to the heat sink.

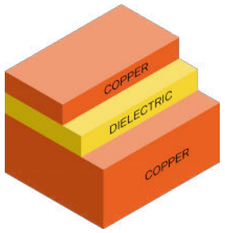
FASTHERM is perfect for conformable MPCB manufacturing.
It can be bent after MPCB production while maintaining the initial dielectric strength in between conductive layers.



FASTHERM technology requires a very accurate and precise depth control to open the thermal pad footprint.

Main features

Insulated Metal Substrate (IMS), based copper clad with RA copper foil on one side.
It is designed for a reliable thermal dissipation of circuitry.



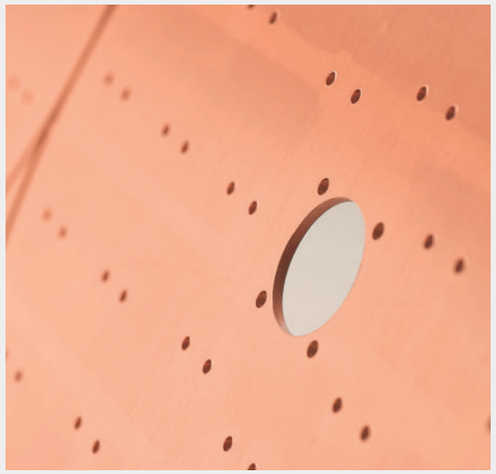
RA copper thickness µm (in)
35 (1oz) / 70 (2oz)

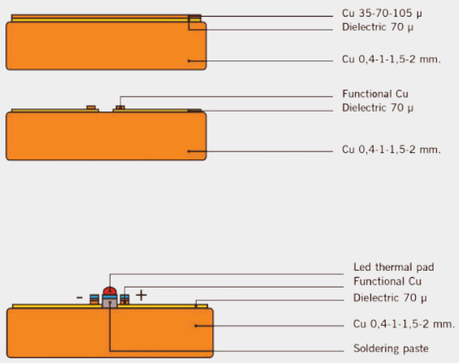
Insulation thickness µm (in)
25 (0,98 mils) / 35 (1,37 mils)
Dielectric thickness tolerance
+ 10 µm (0.1 mils)

Copper Base
0'4mm / 0'5mm / 0'8mm / 1'0 mm / 1'5mm / 2'0mm / 3'0mm

Product configuration

400	11	60	2	0	0.0	0.7	0.018	237.6	6.040	0.019	0.003	0.006
1000	29	60	2	0	0.0	0.7	0.018	303.5	7.708	0.035	0.05	0.012
1500	43	60	2	0	0.0	0.7	0.018	325.6	8.269	0.048	0.007	0.016
400	11	25	1	0	0.0	0.7	0.018	301.0	7.645	0.014	0.002	0.005
1000	29	25	1	0	0.0	0.7	0.018	345.1	8.764	0.030	0.005	0.010
1500	43	25	1	0	0.0	0.7	0.018	357.2	9.073	0.04.	0.007	0.014





Pedestrian Technology

Time to blister at 288°C, floating solder bath	IEC-61189	sec	>60	>30
Copper Peel strength, after heat shock 20 sec/288°C	IPC-TM 650-2.4.8	N/mm (Lb/inch)	1,5 (16,0)	≥ 1,0 (≥10,3)
Dielectric breakdown voltage, AC (1) Fastherm 25µm	IPC-TM 650-2.5.6.3	kV	2	2
Dielectric breakdown voltage, AC (1) Fastherm 35µm			4	4
Dielectric breakdown voltage AC	IPC-TM 650-2.5.6.3	kV	2	2
Flammability, according UL-94, class	UL-94	Class	V-0	V-0
Thermal Impedance °C-m2/watt Fastherm 25 µm (Dielectric)	Calculated	Kcm²/W (K in²/W)	0,36 (0,055)	0,42 (0,065)
Thermal Impedance °C-m2/watt Fastherm 35 µm (Dielectric)			0,50 (0,078)	0,58 (0,090)
Maximum Operational Temperature		°C	140	130
Aluminium Thermal Conductivity	ASTM-D 5470	W/mK	135	130
Copper Thermal Conductivity	ASTM-D 5470	W/mK	375	380